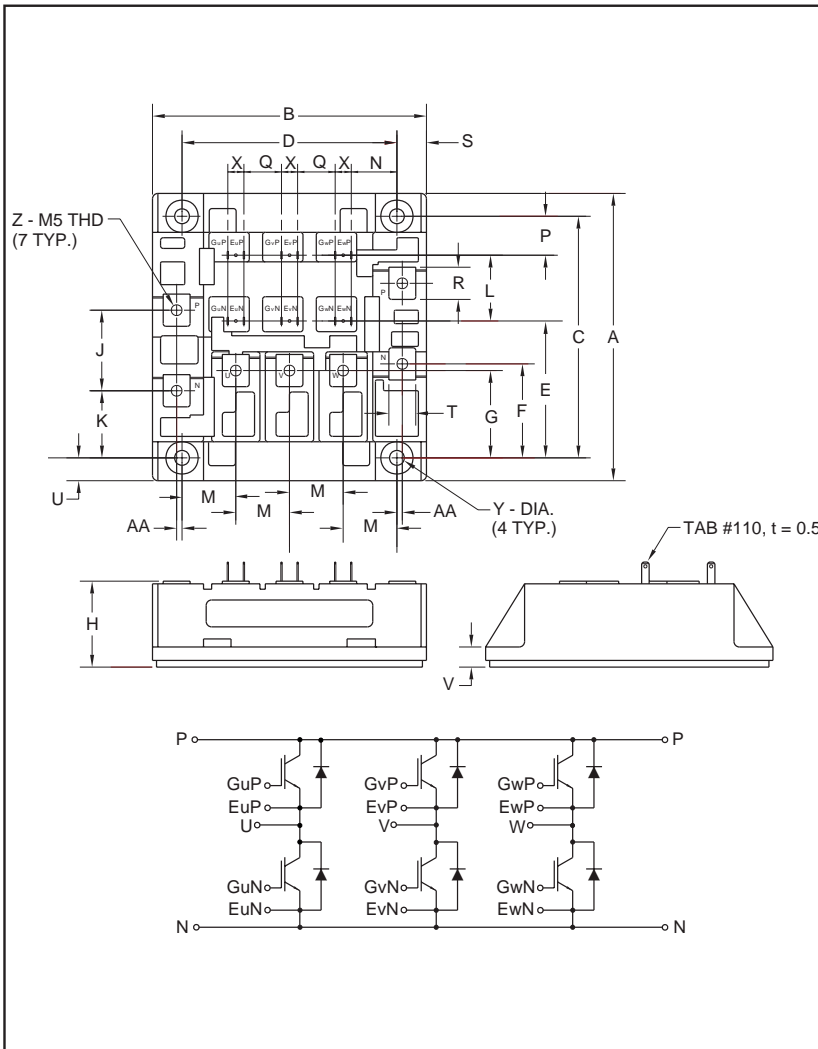


MITSUBISHI IGBT MODULES
CM150TF-12H
 HIGH POWER SWITCHING USE
 INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.21	107.0
B	4.02	102.0
C	3.543±0.01	90.0±0.25
D	3.15±0.01	80.0±0.25
E	2.01	51.0
F	1.38	35.0
G	1.28	32.5
H	1.26 Max.	32.0 Max
J	1.18	30.0
K	0.98	25.0
L	0.96	24.5
M	0.79	20.0
N	0.67	17.0

Dimensions	Inches	Millimeters
P	0.57	14.5
Q	0.55	14.0
R	0.47	12.0
S	0.43	11.0
T	0.39	10.0
U	0.33	8.5
V	0.30	7.5
X	0.24	6.0
Y	0.22	5.5
Z	M5 Metric	M5
AA	0.08	2.0



Description:

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of six IGBTs in a three phase bridge configuration, with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- Low Drive Power
- Low $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- High Frequency Operation
- Isolated Baseplate for Easy Heat Sinking

Applications:

- AC Motor Control
- Motion/Servo Control
- UPS
- Welding Power Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM150TF-12H is a 600V (V_{CES}), 150 Ampere Six-IGBT Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	150	12

CM150TF-12H

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Absolute Maximum Ratings, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

	Symbol	Ratings	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	600	Volts
Gate-Emitter Voltage (C-E SHORT)	V_{GES}	± 20	Volts
Collector Current ($T_C = 25\text{ }^\circ\text{C}$)	I_C	150	Amperes
Peak Collector Current	I_{CM}	300*	Amperes
Emitter Current** ($T_C = 25\text{ }^\circ\text{C}$)	I_R	150	Amperes
Peak Emitter Current**	I_{EM}	300*	Amperes
Maximum Collector Dissipation ($T_C = 25\text{ }^\circ\text{C}$, $T_j \leq 150\text{ }^\circ\text{C}$)	P_C	600	Watts
Mounting Torque, M5 Main Terminal	-	1.47 ~ 1.96	N · m
Mounting Torque, M5 Mounting	-	1.47 ~ 1.96	N · m
Weight	-	830	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V_{iso}	2500	Vrms

*Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.
**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0V$	-	-	1.0	mA
Gate Leakage Current	I_{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0V$	-	-	0.5	μA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 15\text{mA}$, $V_{CE} = 10V$	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 150\text{A}$, $V_{GE} = 15V$	-	2.1	2.8**	Volts
		$I_C = 150\text{A}$, $V_{GE} = 15V$, $T_j = 150\text{ }^\circ\text{C}$	-	2.15	-	Volts
Total Gate Charge	Q_G	$V_{CC} = 300V$, $I_C = 150\text{A}$, $V_{GE} = 15V$	-	450	-	nC
Emitter-Collector Voltage	V_{EC}	$I_E = 150\text{A}$, $V_{GE} = 0V$	-	-	2.8	Volts

** Pulse width and repetition rate should be such that device junction temperature rise is negligible.

Dynamic Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C_{ies}		-	-	15	nF
Output Capacitance	C_{oes}	$V_{GE} = 0V$, $V_{CE} = 10V$	-	-	5.3	nF
Reverse Transfer Capacitance	C_{res}		-	-	3	nF
Resistive	Turn-on Delay Time	$V_{CC} = 300V$, $I_C = 150\text{A}$,	-	-	200	ns
	Load					
Switching	Turn-off Delay Time	$V_{GE1} = V_{GE2} = 15V$, $R_G = 4.2\Omega$	-	-	300	ns
	Times					
Diode Reverse Recovery Time	t_{rr}	$I_E = 150\text{A}$, $di_E/dt = -300\text{A}/\mu\text{s}$	-	-	110	ns
Diode Reverse Recovery Charge	Q_{rr}	$I_E = 150\text{A}$, $di_E/dt = -300\text{A}/\mu\text{s}$	-	0.41	-	μC

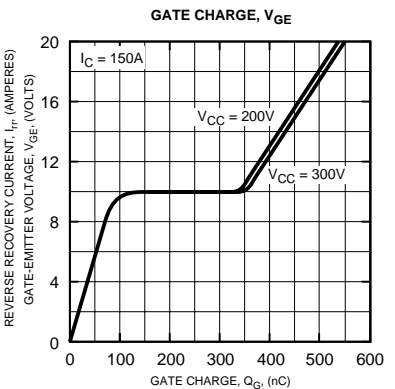
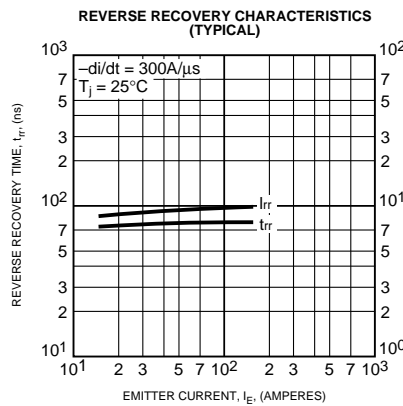
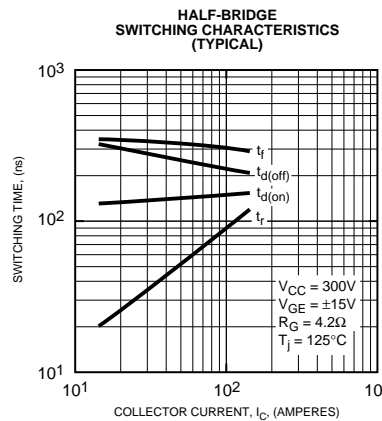
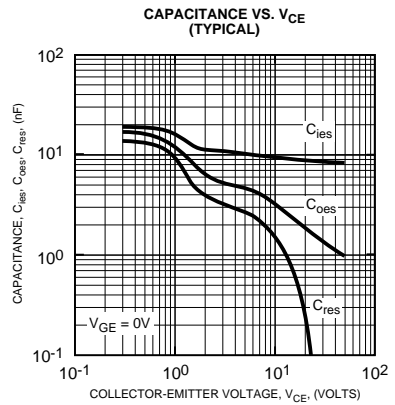
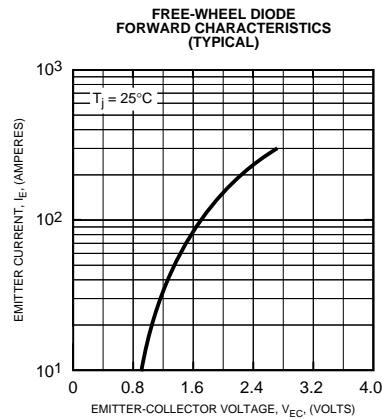
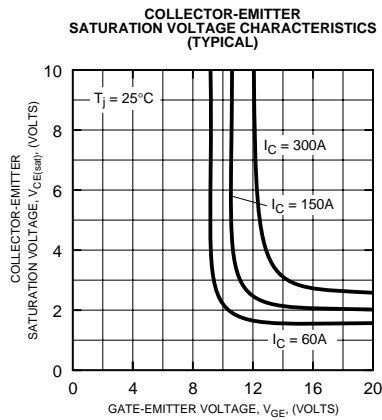
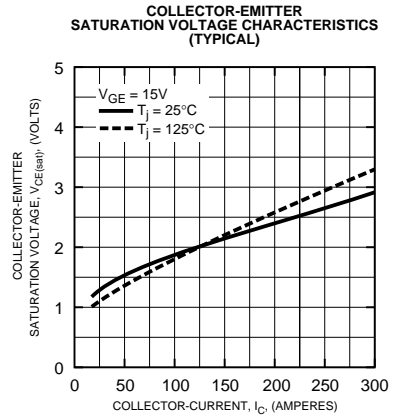
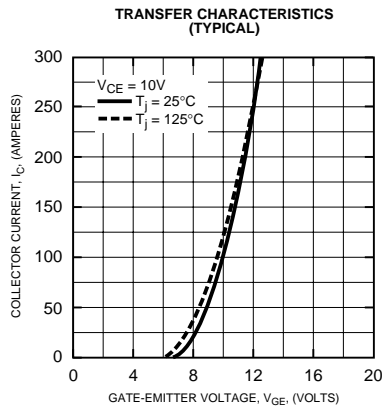
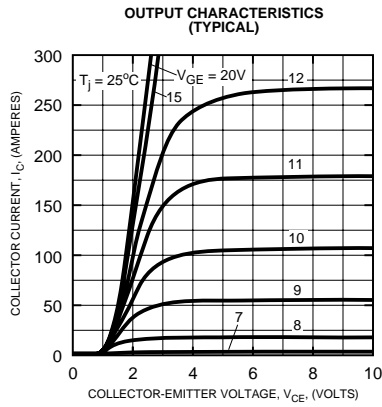
Thermal and Mechanical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per IGBT	-	-	0.21	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per FWDi	-	-	0.47	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	-	-	0.025	$^\circ\text{C}/\text{W}$



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